

# **RRT-3UVPX-NVMe-R-A 3U VPX Air Cooled Carrier with** PCIe Interface and Removable **NVMe SSD Module**

- Capacities up to 16 TB
- 3940 MB/S Transfer rates
- Removable SSD module
- OpenVPX Fat Pipe (FP) PCIe x4 interface
- 100,000 mating cycles
- VITA 65 Slot Profiles:
  - SLT3-PAY-1F1U1S1S1U1U2F1H-14.6.11
    - VPX P1 EP00-EP03 OR
    - VPX P1 EP04-EP07
  - SLT3-PER-1F-14.3.2
- VITA 46, 47, 48, 65
- Boot and/or storage disk
- Air cooled
- COTS NVMe SSDs
- Military erase options
- FIPS140-2, FIPS197, TCG Opal options
- Option for thumbscrews to remove drive module without tools

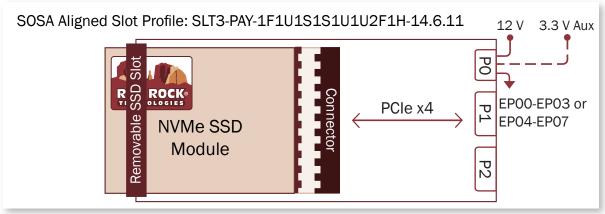
**PARHELIA** 

- PC kit available to connect drive module to PC
- VxWorks, Linux and Windows support



3U VPX AIR COOLED CARRIER WITH PCIE INTERFACE AND REMOVABLE NVME SSD MODULE is for applications that require the frequent removal of SSD, fast transfer rates and large capacities. It consists of two components: the 3U VPX carrier board with PCI express (PCIe) interface to VPX backplane that mounts in one slot of 3U VPX chassis and the removable NVMe SSD module. The connectors between the drive module and the carrier are rated for 100,000 mating cycles to support frequent insertions and removals.

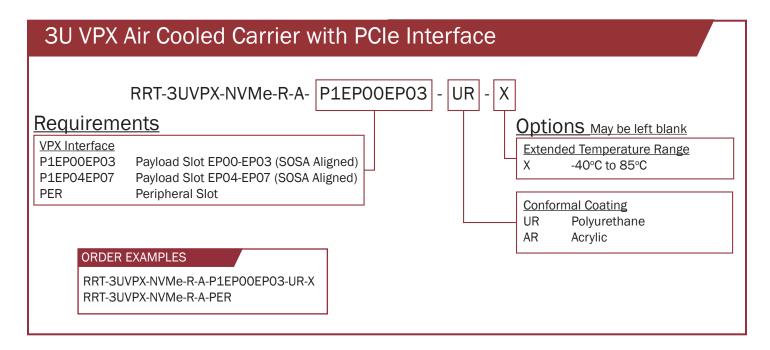
The NVMe SSD module can use any COTS NVMe Solid State Drive (SSD) providing capacities up to 16TB and transfer rates of up to 3940 MB/S. Options for FIPS140-2, FIPS197, TCG Opal, and military erase.

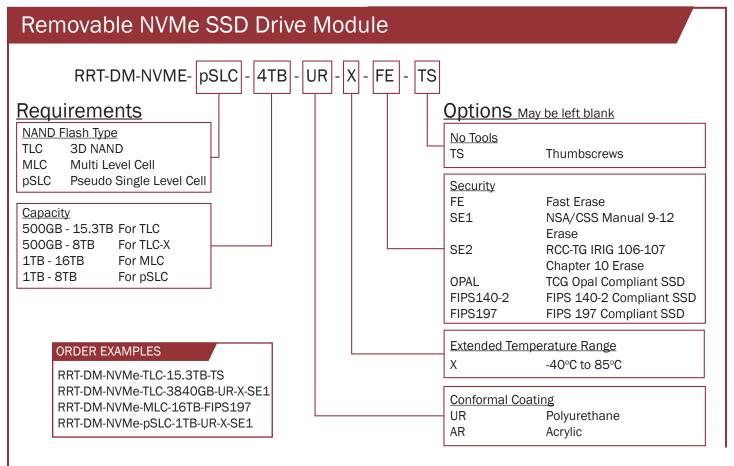






## Ordering Information







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## **Product Specifications**

#### 3U VPX AIR COOLED CARRIER WITH PCIE INTERFACE AND REMOVABLE NVME SSD MODULE

INTERFACE <sup>2</sup> PCI6 THROUGHPUT - SUSTAINED 350	to 15.3TB e Gen 3/4 x 4 DOMB/S (Gen3), DOMB/S (Gen4)	MLC Up to 16TB PCle Gen 2 x 4 800 MB/S	pSLC Up to 4TB	TLC-X Up to 8TB PCle Gen 3 x 4
INTERFACE <sup>2</sup> PCIe THROUGHPUT - SUSTAINED 350	e Gen 3/4 x 4 DOMB/S (Gen3), DOMB/S (Gen4)	PCIe Gen 2 x 4 800 MB/S		PCle Gen 3 x 4
THROUGHPUT - SUSTAINED 350	00MB/S (Gen3), 00MB/S (Gen4)	800 MB/S	1000 MB/S	
	OOMB/S (Gen4)	,	1000 MB/S	
	RELIA			1500MB/S
RELIABILITY				
MTBF - DRIVE 1 m	1 million hours		2 million hours	
MTBF - VPX BOARD <sup>3</sup> 3 m	3 million hours			
DATA RETENTION 1 ye	1 year		5 years	1 year
ENDURANCE (100GB) TOTAL BYTES 70 TWRITTEN	70 TBW		250 TBW	70 TBW
CARRIER/DRIVE MODULE MATING CYCLES  100	100,000 mating cycles			
POWER				
VOLTAGE - PAYLOAD SLOT +12	+12V, +3.3V Aux			
VOLTAGE - PERIPHERAL SLOT 12V	12V +/- 5%, +5V +/- 5%, +3.3V +/- 5%			
WATTS (IDLE) 7 W	V	1.5 W		
WATTS (ACTIVE) 20 V	W	10 W		
ENVIRONMENTAL				
OPERATING TEMP., VITA 47 CLASS <sup>4</sup> 0° C	0°C to 55°C, AC1		0°C to 60°C, AC1	See TLC
EXT. OPERATING TEMP., VITA 47 CLASS <sup>4</sup>   See	e TLC-X	Not available	-40°C to 85°C, AC3	
STORAGE TEMP40	-40°C to 85°C			
ALTITUDE 10,0	10,000 ft. (3,000 meters)		80,000 ft. (24,000 meters)	
RELATIVE HUMIDITY 5%	5% to 95%			
1 7	20g, 11 millisecond terminal sawtooth pulse, OS1		40g, 11 millisecond terminal sawtooth pulse, OS2	
VIBRATION, VITA 47 CLASS <sup>6</sup> 0.04	0.04 g2/Hz, 5 Hz to 100 Hz, V1		0.1 g2/Hz, 100 Hz to 1000 Hz, V3	
PHYSICAL				
FORM FACTOR 3U	VPX			
WEIGHT 14 c	14 oz. max			
PITCH 1"				

#### **NOTES**

- (1) Larger capacities available as new COTS U.2 NVMe drives released
- (2) Interface connected via compatible slot profile SLT3-PAY-1F1U1S1S1U1U2F1H-14.6.11 OR SLT3-PER-1F-14.3.2
- (3) Telcordia SR-332, issue 3, operating temp (40C), electrical stress (50%), environmental factor (1.0)
- (4) Thermal qualification per MIL-STD-810F, Method 501 Procedure II, and MIL-STD-810F, Method 502, Procedure II
- (5) Shock qualification per MIL-STD-810F, Method 516, Procedure I
- (6) Vibration qualification per MIL-STD-810F, Method 514, Procedure I



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